

Addendum 2022 to the LCTPC MoA:

Preparing for the e^+e^- Collider

Overview

The LCTPC Memorandum of Agreement (MoA), the groups which have signed it and the yearly Addenda are available at <http://www.lctpc.org/e9/e56939/>. The MoA was revised in 2016 and can be found at the above link. Updates in the collaboration are documented in the yearly Addenda; information from the preceding year is repeated here for completeness.

1 2022 Activities

As described in the MoA, the R&D preparation of the LCTPC is proceeding in three phases: **1**-Small Prototypes, **2**-Large Prototypes and **3**-Design. Presently the work is in phase **2** and will move to phase **3** as soon as an e^+e^- collider (Sec. 1.2) is approved.

1.1 The ILD LOI, the DBD and the IDR

The International Large Detector (ILD) Letter of Intent (LOI) was validated in 2009 and was followed by the Detailed Baseline Design (DBD) of the detector in 2013, which was the result of further work on the detector and its engineering. The Technical Design Report (TDR) of the International Linear Collider (ILC) accelerator, also completed in 2013, and the DBD were combined into one document: <https://arxiv.org/abs/1306.6327>.

The ILD Interim Design Report (IDR), <https://arXiv.org/abs/2003.01116> [physics.ins-det] 2 Mar 2020, was produced in order to compile the latest information about the physics potential, the sub-detector R&D, the machine-detector interface and the costing.

1.2 The e^+e^- Collider Projects

The LCTPC properties were originally R&Ded for the Tesla linear collider (<https://slidetodoc.com/tesla-linear-collider-project-overview-and-linac-technology/>), after which the work continued for the ILC, both with superconducting cavities and for energies $\sqrt{s} \simeq 0.09$ -1.0 TeV.

The ILC is envisaged to be staged: The first stage, at ~ 250 GeV (precision measurements of the Higgs and related quantities to find indications of Beyond-the-Standard-Model (BSM) physics, is expected to last about a decade. With additional funding, the machine can be upgraded to stages at ~ 350 GeV to ~ 1000 GeV for further precision measurements of the top quark, gauge-boson couplings, Higgs self-coupling, and search for BSM. Moreover, the ‘Giga-Z’ measurement, in which 10^9 Z-bosons are produced at the Z-peak with **polarized beams**, is under serious study by machine and detector physicists. Progress is regularly reported in the ‘LC Newline’ <http://newline.linearcollider.org>.

Other collider projects are under study. They are summarized and evaluated in <https://arXiv.org/abs/2208.06030> [physics.acc-ph] 11 Aug 2022. The e^+e^- collider proposals from 90 GeV - 1 TeV, include ILC,¹ CEPC,² CERC,³ CLIC,⁴ ERLC,⁵ FCC-ee,^{6,7} ILC with upgraded luminosity,⁸ ReLiC.⁹

¹<https://arXiv.org/abs/1306.6352>

²<https://arXiv.org/abs/2203.09451>

³<https://arXiv.org/abs/2203.07358>

⁴<https://arXiv.org/abs/2203.09186>

⁵Journal of Instrumentation 16 (2021) P12025.

⁶Eur. Phys. J. C 79 (2019) 474

⁷<https://arXiv.org/abs/2203.08310>

⁸<https://arXiv.org/abs/2203.07622>

⁹<https://arXiv.org/abs/2203.06476>

At the ILD group meeting in Hamburg on Nov. 8, 2022 (<https://agenda.linearcollider.org/event/9849/>), it was decided that the performance of an “ILD-like” detector at other colliders (than ILC) should be studied.

This is now happening for CEPC and FCC-ee.

1.3 The ILC International Development Team (IDT)

The collaboration and leadership, the international ‘Linear Collider Collaboration’ (LCC) with oversight committee ‘Linear Collider Board’ (LCB), were established to guide the efforts of the ILC, an arrangement that was approved by ICFA (International Committee for Future Accelerators).

On August 2, 2020, ICFA announced the replacement of the LCC and LCB by the IDT as the first step towards the preparatory phase of the ILC project, with a mandate to make preparations for the ILC Pre-Lab in Japan; see ICFA_Statement_August_2020.pdf at <https://icfa.fnal.gov/>. In June 2021 the IDT submitted its report to ICFA describing the organization of the Pre-Lab: see <https://arxiv.org/abs/2106.00602>. The IDT is not yet approved and is now under study by the Japanese government,

2 Responsibilities

Present groups and Collaboration Board members are:

2.1 Collaboration Board (CB) – Table 1

–Americas–

Carleton/Triumf:

Carleton U:

Victoria:

BNL:

Stony Brook:

–Asia———

Tsinghua:

IHEP:

Saha Kolkata:

Hiroshima:

Iwate:

KEK:

Kindai:

Saga:

Kogakuin:

Nagasaki Inst AS:

–Europe———

Inter U Inst for HEP(ULB-VUB):

CEA Saclay:

Bonn:

DESY/HH:

Kiev:

MPI-Munich:

Siegen:

Nikhef:

Lund:

Madhu Dixit msd@physics.carleton.ca

Alain Bellerive alainb@physics.carleton.ca

Dean Karlen karlen@uvic.ca

Alexei Lebedev alebedev@bnl.gov

Klaus Dehmelt klaus.dehmelt@stonybrook.edu

Zhi Deng dengz@mail.tsinghua.edu.cn

Huirong Qi qihr@ihep.ac.cn

Supratik Mukhopadhyay supratik.mukhopadhyay@saha.ac.in

Tohru Takahashi tohru-takahashi@hiroshima-u.ac.jp

Shinya Narita narita@iwate-u.ac.jp

Keisuke Fujii keisuke.fujii@kek.jp

Yukihiro Kato katoy@phys.kindai.ac.jp

Akira Sugiyama sugiyama@cc.saga-u.ac.jp

Takashi Watanabe takashi.watanabe@map.kogakuin.ac.jp

Ken Oyama oyama_ken@nias.as.jp

Gilles De Lentdecker gilles.de.lentdecker@ulb.ac.be

Paul Colas paul.colas@cea.fr

Jochen Kaminski/Klaus Desch

kaminski@physik.uni-bonn.de/desch@physik.uni-bonn.de

Ties Behnke ties.behnke@desy.de

Oleg Bezshyyko obezsh@gmail.com

Ron Settles settles@mpp.mpg.de

Ivor Fleck fleck@hep.physik.uni-siegen.de

Peter Kluit p.kluit@nikhef.nl

Leif Jönsson leif.jonsson@hep.lu.se

2.2 Observers

‘Observers’ are groups or persons that could not sign the MoA but are being informed as to the progress, thus are included in the lctpc mailing list. **Change of status** from ‘collaboration member’ to ‘observer’ is possible and has taken place several times.

Observer groups (collaboration members which changed status in bold):

Americas: **Cornell, Indiana**, LBNL, Louisiana Tech, **Montreal**, MIT, Purdue, Yale.

Asia: Mindanao, U Tokyo, **Tokyo U A & T**.

Europe: **Aachen**, Bucharest, **CERN**, Freiburg, Karlsruhe, UMM Krakow, **LAL Orsay/IPN Orsay**, **Novosibirsk**, **Rostock**, St.Petersburg, TU Munich.

2.3 New groups

The LCTPC collaboration (<http://www.lctpc.org>) is open to all, and a group wishing to join (or rejoin after **change of status**) should contact us.

3 Further LCTPC Collaboration Information

3.1 Regional Coordinators (RC)

The RCs for 2007-2021 after selection of candidates in each region were elected by the CB members of the respective region. Previous RCs were

–Americas: **Dean Karlen** in 2007-10,

Alain Bellerive in 2011 to present, now acting RC until replacement is found,

–Asia: **Takeshi Matsuda** in 2007-09,

Akira Sugiyama in 2010 to 2021,

Shinya Narita in 2021 to present.

–Europe: **Ron Settles** in 2007,

Jan Timmermans in 2008-11,

Jochen Kaminski in 2012 to present.

Spokesperson selection: The RCs do not to have a predetermined rotation of RCs as their chairperson and spokesperson for the collaboration; he/she will be chosen by the RCs. Ron Settles had this function in 2007, and Jan Timmermans was elected as Chairperson/Spokesperson for 2008-11. Jochen Kaminski was chosen by the RCs as the Spokesperson for the following years up to present.

3.1.1 CB Chair

In 2009, the Collaboration Board decided that each year it will appoint one member to chair its meetings for a period of two years. Leif Jönsson agreed to chair the CB meetings in 2012-15, and was reappointed for this task in 2016-2018. Ivor Fleck replaced him in 2018.

3.1.2 Editorial Board (EB)

The purpose of the EB is to approve publications of the collaboration.

The EB is presently made up of: Ties Behnke, Madhu Dixit, Takahiro Fusayasu, Keisuke Fujii, Leif Jönsson, Jochen Kaminski, Takeshi Matsuda, Ron Settles, Sinya Narita and Jan Timmermans. Takahiro Fusayasu agreed to chair the EB in 2016 to present. The most recent R&D study is available at <https://arxiv.org/abs/2205.12160>.

3.1.3 Speakers Bureau

The speakers bureau, installed in 2009 by the CB to monitor the LCTPC presentations at major conferences, is made up of the the three regional coordinators and one additional person per region. The RCs in 2009 were Jan Timmermans, Takeshi Matsuda and Dean Karlen; the persons per region were Paul Colas

as chair up to December 2010, Yuaning Gao and Dan Peterson. The RCs that followed were Jochen Kaminski, Akira Sugiyama and Alain Bellerive and the regional persons were Jan Timmermans, Yulan Li and Dan Peterson in 2011-13; David Attie replaced Jan Timmermans in 2014. Dan Peterson chaired the meetings in 2012, Alain Bellerive for one year starting mid-2013, followed by David Attie mid-2014. Serguei Ganjour was chair in 2018-2019. Maxim Titov (maxim.titov@cea.fr) took over the chair in 2020. Huirong Qi agreed to be the regional person for Asia in 2021.

3.2 Technical Board (TB)

Originally, there were four original workpackages in the MoA (WP(1) Mechanics, WP(2) Electronics, WP(3) Software, WP(4) Calibration); these were supplemented by a fifth workpackage (WP(5) Coordination) in 2010 to prepare for the DBD; with the DBD finished, WP(5) will now oversee the R&D.

The WP(1)-WP(4) structure was utilized at the beginning of the LCTPC collaboration, with individual workpackages meetings to discuss their issues. The structure is out-of-date now and is repeated here for historical completeness. Therefore the ‘conveners’ will be referred to as ‘contacts’.

There are bi-weekly R&D meetings for the LCTPC collaboration, convened by the collaboration spokesperson Jochen Kaminski. There are also regular meetings of the Asian groups and of the pixel groups.

The **TB members**, the ‘contacts’ for the workpackages and their email addresses, and the groups involved:

Table 2	
Workpackage	→ Groups involved Contact
Workpackage(0) TPC R&D Program	LCTPC collaboration
Workpackage(1) Mechanics	
a) LP endplate design and – Fieldcage development	→ Cornell,Bonn, Desy/HH,Japan/China,MPI,Saclay up to 2017 Dan Peterson daniel.peterson@cornell.edu →BNL,Desy/HH Ties Behnke ties.behnke@desy.de
b) GEM panels for endplate	→Bonn,Desy/HH,Japan/China Akira Sugiyama sugiyama@cc.saga-u.ac.jp
c) MicroMegas panels for endplate	→Carleton,IHEP,SahaKolkata,Saclay Paul Colas paul.colas@cea.fr
d) Pixel panels for endplate	→Bonn,Nikhef,Saclay Jan Timmermans jan.timmermans@nikhef.nl
e) Resistive anode for endplate	→Carleton,SahaKolkata,Saclay Madhu Dixit msd@physics.carleton.ca
Workpackage(2) Electronics	
a) Standard RO for the LP	→ Brussels,Cern,Desy/HH,Lund Leif Jönsson leif.jonsson@hep.lu.se
b) CMOS RO electronics	→ Bonn,Nikhef,Saclay Harry van der Graaf vdgraaf@nikhef.nl
c) Standard electronics for LCTPC	→ Brussels,Desy/HH,Lund, up to 2010 Luciano Musa luciano.musa@cern.ch

Workpackage(3) Software

- a) LP software/simulation/reconstruction → Bonn,Cern,Desy/HH,Victoria
up to 2014 **Astrid Muennich** astrid.muennich@desy.de
- b) LP DAQ →Brussels,Lund
Gilles De Lentdecker gilles.de.lentdecker@ulb.ac.be
- c) LCTPC performance/backgrounds → Bonn,Carleton,Cern,Desy/HH,Japan/China
Keisuke Fujii keisuke.fujii@kek.jp

Workpackage(4) Calibration

- a) Field map for the LP → Cern,Desy/HH
Lucie Linsen lucie.linszen@cern.ch
- b) Alignment → Cern,Desy/HH,Nikhef,JapaneseGroups
Takeshi Matsuda takeshi.matsuda@kek.jp
- c) Distortion correction → Desy/HH,MPI,JapaneseGroups,Nikhef,Victoria
Dean Karlen karlen@uvic.ca
- d) Gas/HV/Infrastructure for the LP → Desy/HH,Saclay
up to 2010 **Klaus Dehmelt** klaus.dehmelt@stonybrook.edu
Ralf Diener ralf.diener@desy.de

WP(5) Coordination of LCTPC R&D

- a) Advanced endcap and fieldcage → Desy/HH,Japan/China,MPI,Saclay
Ties Behnke ties.behnke@desy.de
- b) Advanced endcap/Electronics development →Cern,Japan/China,Lund,Nikhef,Saclay
Anders Oskarsson anders.oskarsson@hep.lu.se
Leif Jönsson leif.jonsson@hep.lu.se
up to 2010 **Luciano Musa** luciano.musa@cern.ch
2011 **Eric Delagnes** eric.delagnes@cea.fr
- Advanced endcap/power pulsing/cooling →Desy,Japan/China,Lund,Nikhef,Saclay
Takahiro Fusayasu fusayasu@cc.saga-u.ac.jp
- c) Gating device → JapaneseGroups
Akira Sugiyama sugiyama@cc.saga-u.ac.jp
- d) ILD TPC Integration/Mach-Det Interface → Desy/HH,MPI,Saclay
Volker Prahl volker.prahl@desy.de
Ron Settles settles@mpp.mpg.de
- e) ILD Contacts
Paul Colas paul.colas@cea.fr
up to 2021 **Akira Sugiyama** sugiyama@cc.saga-u.ac.jp
Shinya Narita narita@iwate-u.ac.jp
- f) LCTPC Software/Correction methods →Bonn,Carleton,Desy/HH,JapaneseGroups
up to 2014 **Astrid Muennich** astrid.muennich@desy.de
from 2018 analysis coordinators:
Paul Colas paul.colas@cea.fr
and **Peter Kluit** p.kluit@nikhef.nl
from 2018 MarlinTPC coordinator
Oliver Schaefer oliver.schaefer@desy.de
- g) Pixel-Module Development →Bonn,Carleton,Nikhef,Saclay
up to 2015 **Michael Lupberger** michael.lupberger@cern.ch
Jochen Kaminski kaminski@physik.uni-bonn.de
from 2018 **Peter Kluit** p.kluit@nikhef.nl
- h) Testbeam → all groups
Ralf Diener ralf.diener@desy.de
- Lykoris → Desy/HH
Uwe Krämer uwe.kraemer@desy.de

4 Future R&D, the LP and SPs

4.1 What has been learned

As written in Section 1, the R&D is proceeding in three phases: (1) Small Prototypes–SP, (2) Large Prototypes–LP and (3) Design.

Up to now during Phase(1), a summary of what has been learned:

- the MWPC option ruled out,
- the resistive-anode charge-dispersion technique demonstrated,
- the MicroMegas option without resistive anode ruled out,
- gas properties well measured; the best drift-gas selected,
- the best possible point resolution achieved,
- reliable assemblies of GEM-modules and MicroMegas-modules developed,
- CMOS pixel RO technology successfully demonstrated,
- the dE/dx resolution confirmed,
- gating device developed,
- two phase CO₂ cooling tested.

Therefore the baseline options are MicroMegas with resistive anode with standard electronics, or GEM with standard electronics, or Pixel (= MicroMegas integrated on a Timepix chip).

The Phase(2) LP and SP tests are expected to continue and will be followed by Phase(3), the design of the LCTPC. A scenario for Phase(2) options is presented below in Table 3.

4.2 Review of the ILD TPC R&D

The TPC R&D program and status has been reviewed several times, most recently by the ECFA Panel at Desy on Nov.4, 2013, at which the TPC gave a complete update of the situation. The Review Report is available as LC Note LC-DET-2014-001 at <http://www-f1c.desy.de/lcnotes>.

4.2.1 2014 - 2022

Scenarios for the preliminary, improved and ‘final’ stages of R&D at the LP are summarized in the Table 3. Supplemental testing with SPs, which have been used extensively to date by the LCTPC collaboration (Section 4.1).

Table 3		Scenarios, updated November 2022
Device	Lab(years)	Large Prototype R&D Configuration
Preliminary	Desy(2013-15)	Fieldcage⊕first endplates: GEM, MicroMegas, or Pixel <i>Purpose: Test construction techniques using several thousand pad read-out channels using the Desy test-beam over 70cm tracklength, including development of correction procedures.</i>
Improved	Desy(2016-20)	Fieldcage⊕thinned endplate: GEM, MicroMegas, or Pixel <i>Purpose: Continue tests using several thousand pad read-out channels using the Desy test-beam 70cm tracklength using LP1 thinned endplate and external detector. If possible, simulate a jet-like environment. Pixels tested the ‘100-chip’ LP-module.</i>
Final	LCTPC(after 2022) Collaboration	Fieldcage⊕advanced-endcap prototype: GEM, MicroMegas, or Pixel <i>Purpose: Prototype for LCTPC design based on R&D results for items that are ready: mechanics, electronics, cooling, power pulsing, gating, and fieldcage</i>

Review of the TPC design, performance and engineering issues result in a constant reassessment of the R&D priorities. This Table 4 gives a short overview:

Table 4

- Continue tests in the Desy test-beam to perfect calibration procedures and to improve point resolution, two-point separation, dE/dx resolution
- Continue to design/test gating device
- Endplate/module/fieldcage studies with a maximum of 25% X0 in the endplate including electronics/cooling
- Electronics development
- Powerpulsing and cooling tests

More discussions on the tasks ahead were held at workpackage meetings 176/185/222/258 where more details can be found. The links for these meetings are

176–<http://agenda.linearcollider.org/event/6097/>

185–<http://agenda.linearcollider.org/event/6251/>

222–<http://agenda.linearcollider.org/event/6786/>

258–<http://agenda.linearcollider.org/event/7510/>

The latest update took place at the collaboration meeting on January 14, 2020. The detailed list of issues can be found in the document `22_planlist_new.pdf` at <https://agenda.linearcollider.org/event/8362/contributions/45066/>.

4.2.2 After 2022

After one of the collider options has been chosen (Sec. 1.2), a selection must be made from the different technological options – GEM, MicroMegas, resistive anode, Pixel, electronics, gating device, endcap structure, cooling, mechanics, integration – to establish a working model for the design of the LCTPC.¹⁰

4.3 Performance Goals

The ILD collaboration simulated the physics performance of two versions for the detector: a “large” version with 1808 mm TPC outer radius and 3.5T B-field (the standard used up to now) and a “small” version with 1460 mm TPC outer radius and 4T B-field. The Table 5 below is for the “large” version, Table 6 for the “small” version (the values are back-of-the-envelope approximations).^{11 12 13 14}

¹⁰Achieving the best possible performance – momentum resolution, two-track separation, and dE/dx resolution – have been the object of R&D of GEM, MicroMegas, and Pixels technologies during the past decade (e.g. <https://arxiv.org/abs/2205.12160>). The tables below indicate a direction for the next phase of R&D

¹¹The point resolution, 0.1 mm, for this year’s tables was assumed to be the same for GEM and MicroMegas. The value for the pixel option was assumed to be 0.055mm/ $\sqrt{12}$ for zero drift and 0.4mm for maximum drift: the talk at the ILCX2021 workshop

https://agenda.linearcollider.org/event/9211/contributions/58794/attachments/37527/58794/ILCX_pixelTPC_2021.pdf; the reference on p. 22 gives the resolutions on p.23 for both pad and pixel versions which are used for the comparisons shown in Tables 5 and 6.

¹²For the effective track length in both cases, small and large, 100mm has been added to the inner radius and 100mm subtracted from the outer radius, in order to account for fieldcages, mechanics and services.

¹³The overall tracking resolution (including silicon tracking) would be roughly $\simeq 2 \times 10^{-5}$ for the large version and $\simeq 3 \times 10^{-5}$ for the small version. Physics simulations have shown similar performance for the two versions.

¹⁴For this dE/dx simple calculation, the assumption for the pixel TPC is that a track travels from the inner radius at the middle of the TPC ($r, \phi, z \simeq 429mm, \phi = K(constant), 0mm$) to the outer radius near the endcap ($r, \phi, z \simeq 1700mm(large), \phi = K, 2200mm$), ($r, \phi, z \simeq 1300mm(small), \phi = K, 2200mm$), that three-fourths to one-half of the track length ($ld \equiv$ long drift) uses the standard dE/dx (truncated mean) estimation with a resolution of $\sigma_{ld} \simeq 5\%$ and that one-fourth to one-half ($sd \equiv$ short drift) uses cluster counting with a resolution of $\sigma_{sd} \simeq 3\%$. The weighted mean is calculated with weights $\frac{1}{\sigma_{ld}^2}$ and $\frac{1}{\sigma_{sd}^2}$ for the ld and sd , respectively. The two errors are combined in the standard way:

$$\frac{1}{\sigma_{hypotheticaltrack}^2} = \frac{1}{\sigma_{ld}^2} + \frac{1}{\sigma_{sd}^2}.$$

Table 5, large TPC, for pad/pixel electronics

Parameter	
B-field	3.5T
Geometrical parameters	r_{in} r_{out} z 329 mm 1808 mm \pm 2350 mm
Solid angle coverage	Up to $\cos\theta \simeq 0.98$ (10 pad rows)
TPC material budget	$\simeq 0.05 X_0$ including outer fieldcage in r $< 0.25 X_0$ for readout endcaps in z
Number of pads/timebuckets	$\simeq 10^6/1000$ per endcap
<i>Number of pixels/timebuckets</i>	$\simeq 10^9/1000$ per endcap
Pad pitch/ no.padrows	$\simeq 1 \times 6 \text{ mm}^2 / 213$
σ_{point} in $r\phi$	$\simeq 60 \mu\text{m}$ for zero drift, $< 100 \mu\text{m}$ overall
σ_{point} in $r\phi$	$\simeq 0.055\text{mm}/\sqrt{12}$ for zero drift, 0.4mm for max drift
σ_{point} in rz	$\simeq 0.4 - 1.4 \text{ mm}$ (for zero - full drift)
2-hit separation in $r\phi$	$\simeq 2 \text{ mm}$
2-hit separation in rz	$\simeq 6 \text{ mm}$
dE/dx resolution	$\simeq 5 \%$
<i>dE/dx resolution</i>	$\simeq 4 \%$
Momentum resolution at B=3.5 T	$\delta(1/p_t) \simeq 10^{-4}/\text{GeV}/c$ (TPC only)
<i>Momentum resolution at B=3.5 T</i>	$\delta(1/p_t) \simeq 0.8 \times 10^{-4}/\text{GeV}/c$ (60% cov, TPC only)

Table 6, small TPC, for pad/pixel electronics

Parameter	
B-field	4.0T
Geometrical parameters	r_{in} r_{out} z 329 mm 1460 mm \pm 2350 mm
Solid angle coverage	Up to $\cos\theta \simeq 0.98$ (10 pad rows)
TPC material budget	$\simeq 0.05 X_0$ including outer fieldcage in r $< 0.25 X_0$ for readout endcaps in z
Number of pads/timebuckets	$\simeq 5 \times 10^5/1000$ per endcap
<i>Number of pixels/timebuckets</i>	$\simeq 5 \times 10^8/1000$ per endcap
Pad pitch/ no.padrows	$\simeq 1 \times 6 \text{ mm}^2 / 155$
σ_{point} in $r\phi$	$\simeq 60 \mu\text{m}$ for zero drift, $< 100 \mu\text{m}$ overall
σ_{point} in $r\phi$	$\simeq 0.055\text{mm}/\sqrt{12}$ for zero drift, 0.4mm for max drift
σ_{point} in rz	$\simeq 0.4 - 1.4 \text{ mm}$ (for zero - full drift)
2-hit separation in $r\phi$	$\simeq 2 \text{ mm}$
2-hit separation in rz	$\simeq 6 \text{ mm}$
dE/dx resolution	$\simeq 6 \%$
<i>dE/dx resolution</i>	$\simeq 5 \%$
Momentum resolution at B=4 T	$\delta(1/p_t) \simeq 2 \times 10^{-4}/\text{GeV}/c$ (TPC only)
<i>Momentum resolution at B=4 T</i>	$\delta(1/p_t) \simeq 1.6 \times 10^{-4}/\text{GeV}/c$ (60% cov, TPC only)